

74.(NEW) A polishing apparatus according to claim 73, wherein said polishing pressure comprises a fluid pressure.

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75.(NEW) A polishing apparatus according to claim 73, wherein said polishing pressure comprises a compressed air pressure.

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76.(NEW) A polishing apparatus comprising to claim 73, wherein said central area and said outer circumferential area are formed by chambers formed in said top ring.

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77.(NEW) A polishing apparatus according to claim 73, further comprising:
a third area located between said central area and said outer circumferential area.

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78.(NEW) A polishing apparatus according to claim 73, further comprising:
a presser ring disposed around the workpiece and contacting a polishing surface for polishing the workpiece.

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79.(NEW) A polishing apparatus according to claim 78, wherein said presser ring is pressed by pressurized fluid.

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80.(NEW) A method for polishing a workpiece, comprising:
holding a workpiece on a surface of a top ring; and
applying a polishing pressure on a surface of the workpiece, wherein
an area where said polishing pressure is applied is divided to a central area and an outer
circumferential area of the workpiece, and the radial width of said outer circumferential
area is narrower than that of said central area.

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81.(NEW) A method according to claim 80, wherein said polishing pressure
comprises a fluid pressure.

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82.(NEW) A method according to claim 80, wherein said polishing pressure
comprises a compressed air pressure.

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83.(NEW) A method according to claim 80, wherein said central area and said
outer circumferential area are formed by chambers formed in said top ring.

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84.(NEW) A method according to claim 80, wherein the area where said
polishing pressure is applied is divided to said central area, said outer circumferential area
and a third area located between said central area and said outer circumferential area.

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85.(NEW) A method according to claim 80, further comprising:

pressing a presser ring disposed around the workpiece against a polishing surface for polishing the workpiece.

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86.(NEW) A method according to claim 85, wherein said presser ring is pressed by pressurized fluid.

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END

87.(NEW) A polishing apparatus for polishing a surface of a workpiece, comprising:

a turntable having a polishing surface thereon;

a top ring to support the workpiece to be polished on a holding surface of said top ring;

a presser ring vertically movably disposed around said top ring;

a mechanism to move said top ring vertically so that said top ring moves toward and away from said polishing surface;

a pressing mechanism to provide a first pressing force onto the workpiece, said first pressing force being different in a central portion and an outer circumferential portion of the workpiece; and

a pressing device to press said presser ring against said polishing surface under a second pressing force, said second pressing force being independently controllable with respect to said first pressing force.

Constance